

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/05/2022

Details for "SN74AHC157PWRG3"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
SN74AHC157PWRG3	SN	Level-1-260C-UNLIM	Ext-Mfg	PW   16	5x4.4x1.0	58.5

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.119745	97.58612	975861	0.20477	2048
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.000815	8	0.000002	0
Not Categorized	Proprietary Materials		0.000012	0.009779	98	0.000021	0
Precious Metals	Palladium	7440-05-3	0.002945	2.400026	24000	0.005036	50
Precious Metals	Silver	7440-22-4	0.000004	0.00326	33	0.000007	0
Sub-Total			0.122707	100	1000000	0.209835	2098
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.153789	81.999808	819998	0.262987	2630
Thermoplastics	Epoxy	85954-11-6	0.033759	18.000192	180002	0.05773	577
Sub-Total			0.187548	100	1000000	0.320716	3207
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	21.29625	94.65	946500	36.417641	364176
Magnesium and Its Alloys	Magnesium	7439-95-4	0.039375	0.175	1750	0.067333	673
Nickel and Its Alloys	Nickel	7440-02-0	0.72	3.2	32000	1.231236	12312
Other inorganic Materials	Silicon	7440-21-3	0.163125	0.725	7250	0.278952	2790
Precious Metals	Silver	7440-22-4	0.28125	1.25	12500	0.480951	4810
Sub-Total			22.5	100	1000000	38.476113	384761
<b>Lead Frame Plating</b>							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.45	100	1000000	0.769522	7695
Sub-Total			0.45	100	1000000	0.769522	7695
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	29.300024	84.850001	848500	50.10449	501045
Other Plastics and Rubber	Carbon Black	1333-86-4	0.051797	0.149999	1500	0.088575	886
Thermoplastics	Epoxy	85954-11-6	5.179733	15	150000	8.8576	88576
Sub-Total			34.531554	100	1000000	59.050665	590507
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.686032	100	1000000	1.173149	11731
Sub-Total			0.686032	100	1000000	1.173149	11731
<b>Total</b>			58.477841			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former IIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
 Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.